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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







## **IGBT - Short-Circuit Rated**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Non–Punch Through (NPT) Trench construction, and provides superior performance in demanding switching applications. Offering both low on state voltage and minimal switching loss, the IGBT is well suited for motor drive control and other hard switching applications.

#### **Features**

- Low Saturation Voltage Resulting in Low Conduction Loss
- Low Switching Loss in Higher Frequency Applications
- 5 µs Short Circuit Capability
- Excellent Current versus Package Size Performance Density
- This is a Pb-Free Device

#### **Typical Applications**

- White Goods Appliance Motor Control
- General Purpose Inverter
- AC and DC Motor Control

### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	V <sub>CES</sub>	650	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	30 15	А
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	120	Α
Gate-emitter voltage	$V_{GE}$	±20	V
Power dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	117 47	W
Short circuit withstand time $V_{GE} = 15 \text{ V}, V_{CE} = 400 \text{ V}, T_{J} \le +150^{\circ}\text{C}$	tsc	5	μs
Operating junction temperature range	TJ	-55 to +150	°C
Storage temperature range	T <sub>stg</sub>	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

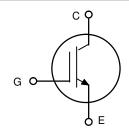
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

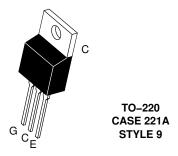


## ON Semiconductor®

www.onsemi.com

15 A, 650 V V<sub>CEsat</sub> = 1.5 V





#### **MARKING DIAGRAM**



A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTG15N60S1EG	TO-220 (Pb-Free)	50 Units / Rail

#### THERMAL CHARACTERISTICS

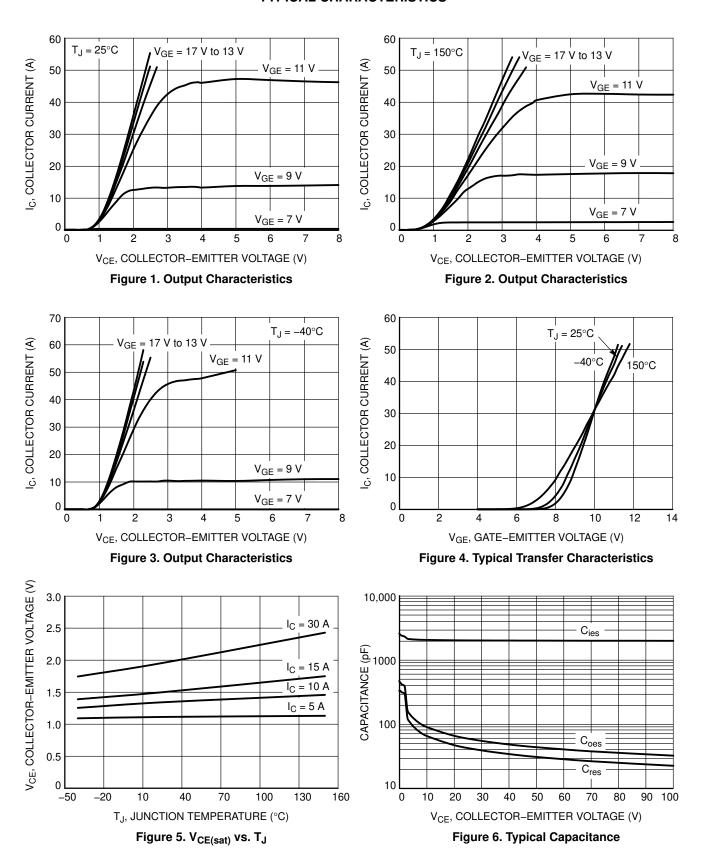
Rating	Symbol	Value	Unit
Thermal resistance junction to case, for IGBT	$R_{ heta JC}$	1.06	°C/W
Thermal resistance junction to ambient	$R_{ hetaJA}$	60	°C/W

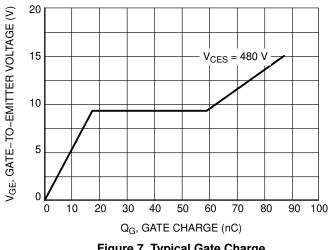
## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE}$ = 0 V, $I_C$ = 500 $\mu A$	V <sub>(BR)CES</sub>	650	-	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V , I <sub>C</sub> = 15 A V <sub>GE</sub> = 15 V , I <sub>C</sub> = 15 A, T <sub>J</sub> = 150°C	V <sub>CEsat</sub>	1.3 1.55	1.5 1.75	1.7 1.95	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 250 \mu A$	V <sub>GE(th)</sub>	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 600 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 600 V, T <sub>J</sub> = 150°C	I <sub>CES</sub>	_ _	10 -	_ 200	μΑ
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	100	nA
Forward Transconductance	$V_{CE} = 20 \text{ V}, I_{C} = 15 \text{ A}$	9fs	-	10.1	-	S
DYNAMIC CHARACTERISTIC						
Input capacitance		C <sub>ies</sub>	-	1950	_	
Output capacitance	$V_{CE} = 20 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$	C <sub>oes</sub>	-	70	-	pF
Reverse transfer capacitance		C <sub>res</sub>	-	48	-	
Gate charge total		Qg	-	88	-	nC
Gate to emitter charge	$V_{CE} = 480 \text{ V}, I_{C} = 15 \text{ A}, V_{GE} = 15 \text{ V}$	Q <sub>ge</sub>	_	16	-	
Gate to collector charge		Q <sub>gc</sub>	-	42	-	
SWITCHING CHARACTERISTIC , INDUCTIVE	LOAD					
Turn-on delay time		t <sub>d(on)</sub>	_	65	-	
Rise time		t <sub>r</sub>	_	28	-	
Turn-off delay time	T <sub>.1</sub> = 25°C	t <sub>d(off)</sub>	-	170	-	ns
Fall time	$T_J = 25^{\circ}C$ $V_{CC} = 400 \text{ V, } I_C = 15 \text{ A}$ $R_0 = 22 \Omega$	t <sub>f</sub>	-	140	-	
Turn-on switching loss	$R_g = 22 \Omega$ $V_{GE} = 0 V / 15 V^*$	E <sub>on</sub>	-	0.550	-	
Turn-off switching loss		E <sub>off</sub>	-	0.350	-	mJ
Total switching loss		E <sub>ts</sub>	-	0.900	-	
Turn-on delay time		t <sub>d(on)</sub>	-	65	-	
Rise time		t <sub>r</sub>	-	28	-	ne
Turn-off delay time	T <sub>J</sub> = 150°C	t <sub>d(off)</sub>	-	180	-	ns
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 15 \text{ A}$ $R_{C} = 22 \Omega$	t <sub>f</sub>	-	260		
Turn-on switching loss	$R_g = 22 \Omega$ $V_{GE} = 0 V / 15 V^*$	E <sub>on</sub>	_	0.650	-	
Turn-off switching loss		E <sub>off</sub>	-	0.600	-	mJ
Total switching loss		E <sub>ts</sub>	_	1.250	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

\*Includes diode reverse recovery loss using NGTB15N60S1EG.

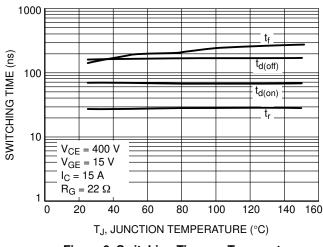




0.7 Eon 0.6 SWITCHING LOSS (mJ) 0.5 Eoff 0.4 0.3 V<sub>CE</sub> = 400 V 0.2  $V_{GE} = 15 V$  $I_{C} = 15 A$ 0.1  $R_G = 22 \Omega$ 0 0 20 40 60 80 100 120 140 160 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 7. Typical Gate Charge

Figure 8. Switching Loss vs. Temperature



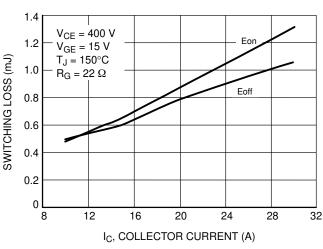
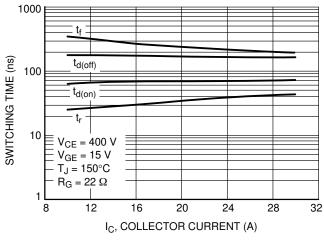


Figure 9. Switching Time vs. Temperature

Figure 10. Switching Loss vs. I<sub>C</sub>



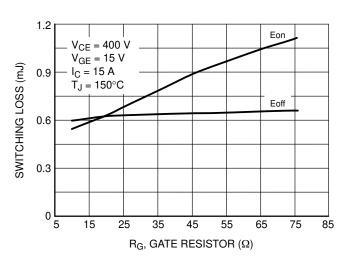


Figure 11. Switching Time vs. I<sub>C</sub>

Figure 12. Switching Time vs. R<sub>G</sub>

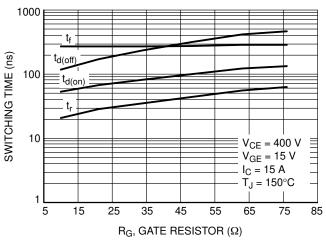


Figure 13. Switching Time vs. R<sub>G</sub>

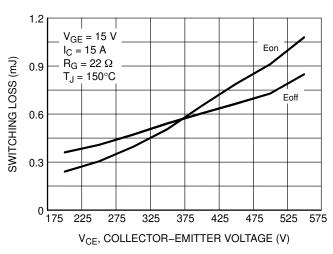


Figure 14. Switching Loss vs. V<sub>CE</sub>

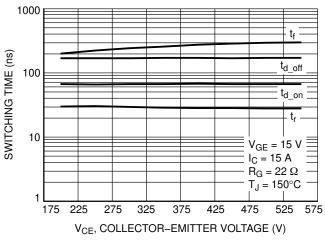


Figure 15. Switching Time vs. V<sub>CE</sub>

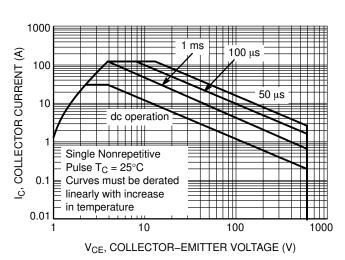


Figure 16. Safe Operating Area

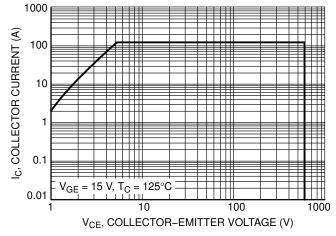


Figure 17. Reverse Bias Safe Operating Area

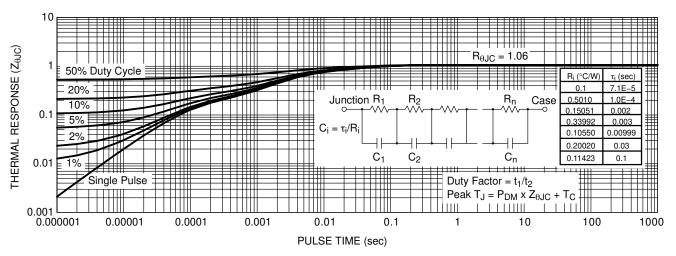


Figure 18. IGBT Transient Thermal Impedance

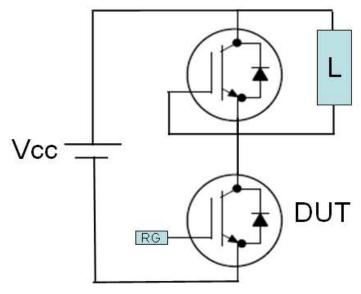


Figure 19. Test Circuit for Switching Characteristics

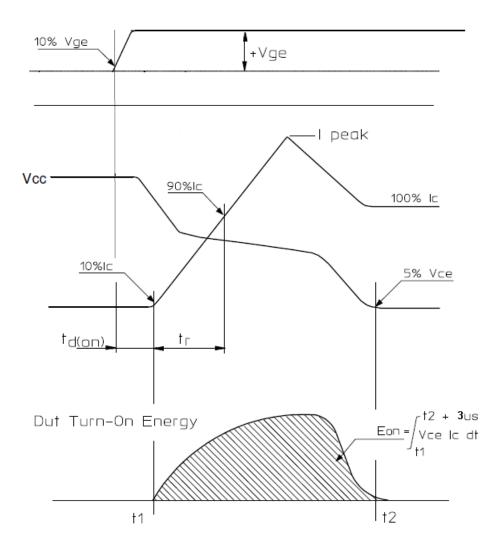


Figure 20. Definition of Turn On Waveform

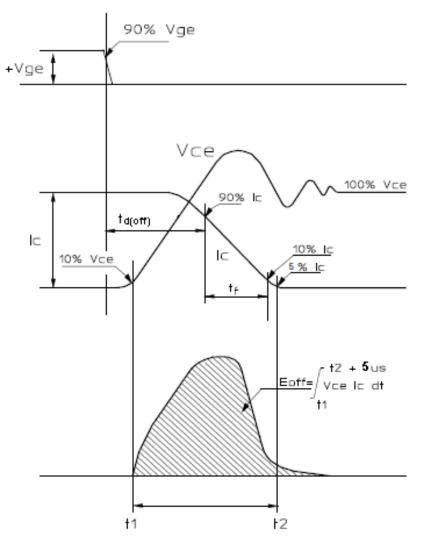
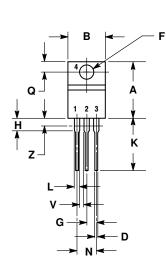
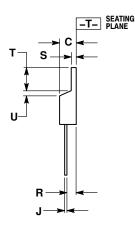


Figure 21. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH** 





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- CONTROLLING DIMENSION: INCH.
  DIMENSION Z DEFINES A ZONE WHERE ALL
  BODY AND LEAD IRREGULARITIES ARE ALLOWED

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.415	9.66	10.53	
С	0.160	0.190	4.07	4.83	
D	0.025	0.038	0.64	0.96	
F	0.142	0.161	3.61	4.09	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.161	2.80	4.10	
7	0.014	0.024	0.36	0.61	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
T	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

STYLE 9:

- PIN 1. GATE
  - 2. COLLECTOR
  - **EMITTER**
  - COLLECTOR

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